



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

Datum:

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**PRINTED CIRCUIT BOARDS**

**01**

**4.11.2001**

**1/1**

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 157 FR4 35 L71.35 P18\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_157\_FR4\_35\_L71.35\_p18\_06**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	35 $\mu$	Copper			
	60 $\mu$	Prepreg			(60 $\mu$ PrePreg-Type: 1080 )
	60 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
	180 $\mu$	Prepreg			(180 $\mu$ PrePreg-Type: 7628)
<b>Layer-2</b>	35 $\mu$	Copper			
	710 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			
	180 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
	60 $\mu$	Prepreg			
<b>Layer-99</b>	35 $\mu$	Copper			

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